

IN THE CLAIMS

Please amend the claims to be in the form as follows:

Claim 17 (previously submitted): A circuit board, comprising:

a dielectric substrate;

a plurality of electrically conductive pads connected to the substrate for electrical interconnection of components to the pads;

wiring extending between the pads;

a coil of wire bent into a plurality of sequential loops;

multiple terminals of the coil at respective pads;

an electrically conductive material connecting between the pads and respective terminals;

a surface of material connected to the coils extending over a plurality sequential loops of the coil for pick-up with a vacuum head of a pick-and-place machine, and including adjusting means to allow for adjusting a position of the loops of the coil for turning the coil, after the coil is attached to the circuit board.

Claim 18 (previously submitted): The board of Claim 17 in which the adjusting means includes that at least a portion of the surface can be removed from the wire coil without damaging the wire coil, so that a position of the loops of the coil can be changed to tune the coil.

Claim 19 previously submitted): The board of Claim 17 in which the adjusting means includes that the surface does not extend between all of the loops of the coil so that a position of the loops, between which the surface does not extend, can be changed by bending the coil for tuning the coil.

Claim 20 (previously submitted): The board of Claim 17 in which the adjusting means includes that the surface is sufficiently weak or flexible so that the loops between which the surface extends can be easily bent to adjust a position of the loops sufficient for tuning the coil without otherwise damaging the coil.

Claim 21 (previously submitted): The board of Claim 17 in which the adjusting means includes that the surface is degraded by exposure to a solvent that can be used to wash the circuit board after the coil is connected to the circuit board, whereby the loops can be bent to adjust a position of the loops for tuning the coil.

Claim 22 (previously submitted): The board of Claim 21 in which the adjusting means includes that the surface is degraded by exposing the surface to water and at least a portion of a material of the surface can be removed by washing in water without damaging the coils.

Claim 23 (previously submitted): The board of Claim 17 in which the adjusting means includes that the surface is degraded by heating the circuit board after which the separation between the loops can be changed by bending the loops for tuning the coil.

Claim 24 (previously submitted): The board of Claim 23 in which the adjusting means includes that the material of the surface flows when exposed to soldering temperature of eutectic Pb/Sn alloy, so that after heating the circuit board to reflow the solder at least some of the loops become bendable for tuning the coil.

Claim 25 (previously submitted): The board of Claim 23 in which the adjusting means includes that the material of the surface sublimates when exposed to soldering temperature of eutectic Pb/Sn alloy, so that after reflow soldering the circuit board at least some of the loops become bendable for tuning the coil.

Claim 26 (previously submitted): The board of Claim 17 in which the adjusting means includes that the surface is sufficiently soft and arranged, so that it can be easily cut between loops of the coil using a tool without damaging the coil and then a position of the loops of the coil can be adjusted to tune the coil.

Claim 27 (previously submitted): The board of Claim 17 in which the coils are spaced between 2 and 10 times the diameter of the wire.

Claim 28 (previously submitted): The board of Claim 17 wherein the adjusting means includes that the loops are spaced apart and are of a material such that the position of the loops are adjustable.

Claim 29 (previously submitted): The board of Claim 17 in which:

the adjusting means is selected from one or more of:

at least a portion of the surface can be removed from the wire coil without damaging the wire coil so that a spacing between the loops of the coil can be changed to tune the coil;

the surface does not extend onto some of the loops of the coil so that a position of the loops can be changed by bending the coil for tuning the coil;

the surface is sufficiently weak or flexible so that the loops on which the surface extends can be easily bent to adjust a position of the loops sufficient for tuning the coil without otherwise damaging the coil;

the surface is degraded by exposure to a solvent that can be used to wash the circuit board after the coil is connected to the circuit board whereby the loops can be bent for adjusting a position of the loops for tuning the coil;

the surface is degraded by exposing the surface to water and at least a portion of a material of the surface can be removed by washing in water without damaging the coils;

the surface is degraded by heating the circuit board after which the separation between the loops can be changed by bending the loops for tuning the coil;

the material of the surface flows when exposed to

soldering temperature of eutectic Pb/Sn alloy so that after heating the circuit board to reflow the solder at least some of the coils become mechanically separable for tuning the coil;

the material of the surface sublimates when exposed to soldering temperature of eutectic Pb/Sn alloy so that after reflow soldering the circuit board at least some of the coils become mechanically separable for tuning the coil; and

the surface is sufficiently soft and arranged so that it can be easily cut between loops of the coil using a tool without damaging the coil and then a position of the loops of the coil can be adjusted to tune the coil;

and wherein;

the terminals are strait sections of wire extending tangentially to the loops of wire
at each end of the coil of wire;

the coil is an air coil without any core;

the wire is nearly pure copper;

the wire is between .05 mm and 1 mm in diameter;

the coils are spaced between 1.1 and 20 times the diameter of the wire; and

the diameter of the loops is between 10 and 100 times the diameter of the wire.